# TERMINATION CVD DIAMOND CHIP 125 WATTS



EN 13-3904

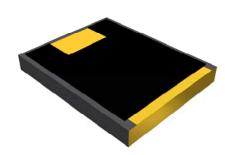
#### DATA SHEET P

### PART SERIES: CT1310D

#### **FEATURES**

# APPLICATIONS

- Small Size Light Weight Highest Thermal Performance Possible Excellent Peak Power Capability Rugged Passivated TaN Film Moisture Resistant Pure Gold Input Pads Wire Bondable or Solderable High Power
- Broadcast Higher Power Filters High Power Amplifiers Instrumentation Isolators Military Satellite Communications Phased Array Radar



Dwg 1010545

# **GENERAL DESCRIPTION**

CVD Diamond Chip Terminations offer a unique combination of extreme high power ratings in very small packages. These terminations may be used in applications up to 30 GHz and are ideal for applications with requirements for high power capability, broad frequency response, small footprint and light weight. The terminations are manufactured using all thin film construction and have a gold finish that it both wire bondable and solderable. This total thin film construction also makes them ideal for peak power applications. High reliability tested versions based on MIL-PRF-55342 are also available. Select from tape and reel, bulk, or waffle packaging. These products are also lead free, RoHS compliant and S-level approved.

## **ORDERING INFORMATION**

Part Identifier: CT1310D

# **SPECIFICATIONS**

# **1.0 ELECTRICAL**

١	Nominal Impedance:	$50 \Omega \pm 5\%$
F	Frequency Range:	DC – 14.0 GHz
I	nput Power CW:	125 Watts
F	Peak Power:	5000 W (1 µs pulse width / 1% duty cycle)
١	/SWR:	1.40:1 Max

# 2.0 ENVIRONMENTAL

Operating Temperature:	-55 °C To +150 °C
Storage Temperature:	-55 °C To +150 °C
Temperature Coefficient:	±200 PPM/°C Max

#### **3.0 MARKING**

Unit Marking:

None

#### **4.0 QUALITY ASSURANCE**

Sample Inspect Per ANSI/ASQC Z1.4 General Inspection, Level II, 1.0% AQL. Visual and Mechanical Inspection for Conformance to Outline Drawing Measure DC Resistance Data Retention - Standard

#### 5.0 PACKAGING

Standard:

Waffle Packaging

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#### DATA SHEET PA

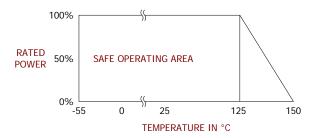
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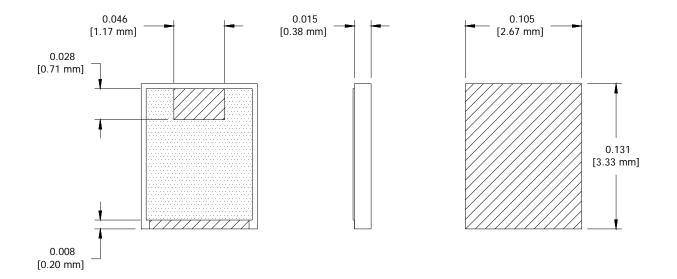
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### 6.0 MECHANICAL

Substrate Material: Terminal Material: Ground Plane Material: Resistive Element: Metric Dimensions:

# CVD Diamond Gold over Nickel Gold over Platinum Thin Film Provided for reference only





Unless Otherwise Specified: TOLERANCE: X.XX = ± 0.01 X.XXX = ± 0.005